

WHAT IS CLAIMED IS:

1. A recognition device comprising:

a substrate setting base, having a heating function;
a cover, which covers a working region from above said substrate setting base;

a working hole, provided in the upper surface of said cover;

an illumination, disposed above said working hole; and
a pattern recognition camera, disposed inside a lens barrel provided above said illumination; wherein

fluctuation of ascending air current, which is due to an inert gas that is blown inside said cover being heated by said substrate setting base, is made to escape in the horizontal direction with respect to said cover surface by a blow current from a blowing device provided at a lower part of said illumination.

2. The recognition device according to Claim 1, wherein said inert gas is made to flow into a space formed by said cover and said substrate setting base.

3. The recognition device according to Claim 1, wherein a part of said cover is formed of a clamper.

4. The recognition device according to Claim 3, wherein said clamper is provided with a blow-in hole for said inert gas.

5. The recognition device according to Claim 1, wherein said fluctuation is substantially that of said inert gas that has been heated.

6. The recognition device according to Claim 1, wherein said inert gas is made of nitrogen gas.

7. The recognition device according to Claim 1, wherein said illumination is a ring-shaped illumination provided below said lens barrel part.

8. A bonding device comprising:

 a substrate setting base, having a heating function;

 a cover, which covers a working region from above said substrate setting base;

 a working hole, provided in the upper surface of said cover;

 an illumination, disposed above said working hole;

 a capillary, disposed at the side face of said

illumination; and

a pattern recognition camera, disposed inside a lens barrel provided above said illumination; wherein

fluctuation of ascending air current, which is due to an inert gas that is blown inside said cover being heated by said substrate setting base, is made to escape in the horizontal direction with respect to said cover surface by a blow current from a blowing device provided below said illumination, and after recognition by said pattern recognition camera, said capillary is moved to above said working hole and bonding is performed via said working hole.

9. The bonding device according to Claim 8, wherein said inert gas is made to flow into a space formed by said cover and said substrate setting base.

10. The bonding device according to Claim 8, wherein a part of said cover is formed of a clamper.

11. The bonding device according to Claim 10, wherein said clamper is provided with a blow-in hole for said inert gas.

12. The bonding device according to Claim 8, wherein said

fluctuation is substantially that of said inert gas.

13. The bonding device according to Claim 8, wherein said inert gas is made of nitrogen gas.

14. The bonding device according to Claim 8, wherein said illumination is a ring-shaped illumination provided below said lens barrel part.

15. A circuit device manufacturing method comprising the steps of:

preparing a block substrate, which is provided with conductive patterns, wherein a plurality of mounting parts and leads are integrated within a small area, and with which circuit elements are affixed respectively onto said mounting parts;

setting said block substrate on a substrate setting base until assembly onto all of said mounting parts is completed;

heating said substrate setting base by a heating function while filling the interior of a cover with an inert gas; and

making the fluctuation of ascending air current, which is due to an inert gas that is blown inside said cover being heated by said substrate setting base, escape in the horizontal direction with respect to said cover surface by a blow current

provided below said illumination, recognizing said circuit elements respectively on said mounting parts by means of a recognition camera installed inside a lens barrel, and wire bonding said circuit elements, respectively on said mounting parts, to said conductive patterns.

16. The circuit device manufacturing method according to Claim 15, wherein a part of said cover is formed of a clamper.

17. The circuit device manufacturing method according to Claim 16, wherein inert gas is blown inside said cover via said clamper.

18. The circuit device manufacturing method according to Claim 15, wherein said fluctuation is substantially that of said inert gas.

19. The circuit device manufacturing method according to Claim 15, wherein said inert gas is made of nitrogen gas.

20. The circuit device manufacturing method according to Claim 15, wherein said circuit elements are one or both of a bare semiconductor chip and a chip circuit part.